

PRODUCT NUMBER

98423-XXX-XXXLF

PLATING

S = 0.38µm GOLD/GXT
ON CONTACT AREA
2µm MIN MATTE
TIN ON TAIL

G = 0.76µm GOLD/GXT
ON CONTACT AREA
2µm MIN MATTE
TIN ON TAIL

F = GOLD FASH
ON CONTACT AREA
2µm MIN MATTE

RoHS COMPATIBLE, SEE NOTE 6

PACKAGING OPTIONAL LETTER (SEE NOTE 5)

NB OF POSITIONS PER ROW
02 TO 25 POS

PIN STYLE	MATING STYLE	SOLDER STYLE
61	4.00	2.50
62	7.00	3.00
63	7.00	3.50

NOTES:

1. MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC
UL 94V-0, COLOR BLACK
2. MATERIAL TERMINAL: COPPER ALLOY
3. TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW
4. 7N MIN. PIN RETENTION IN EITHER DIRECTION.

5. PACKAGING:

- = PLASTIC BOX
- U = TUBE AVAILABLE FROM 06 TO 50 POS

6. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:

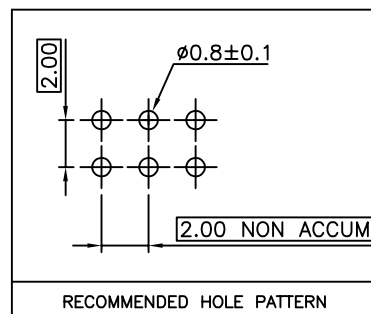
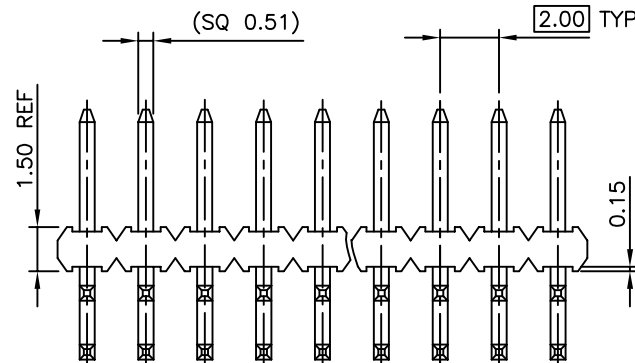
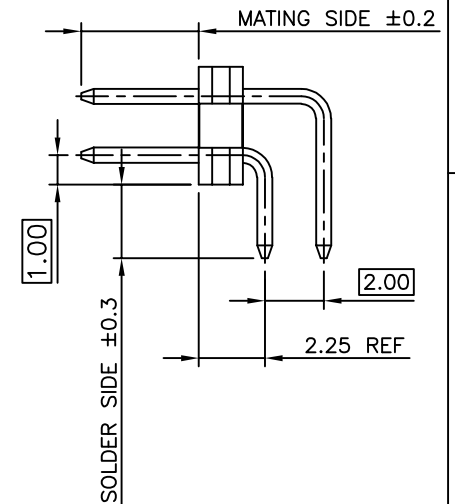
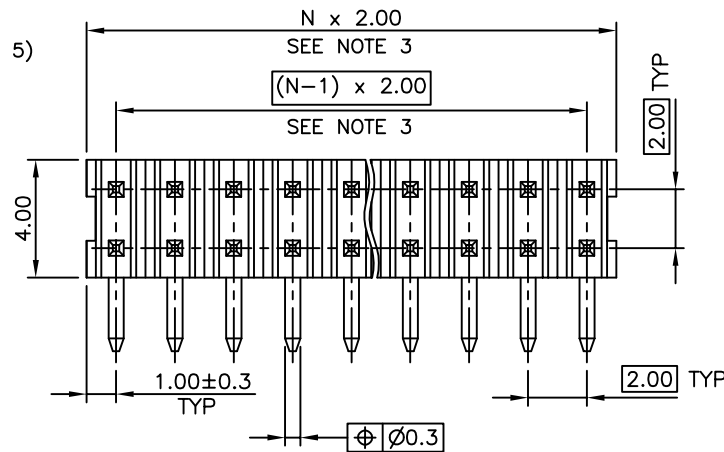
- "LF" MEANS THE PRODUCT IS LEAD-FREE,
2µm MINIMUM MATTE TIN OVER 1.27µm
MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

- THE HOUSING WILL WITHSTAND EXPOSURE TO
260°C ±5°C SOLDER BATH TEMPERATURE FOR
5 SECONDS IN A WAVE SOLDER APPLICATION
WITH A 1.6mm MIN THICK CIRCUIT BOARD.

c - LABELLING:

- MEETS PACKAGING SPECS AS PER GS-14-920
- THIS PRODUCT MEETS EUROPEAN DIRECTIVES
AND OTHER COUNTRY REGULATIONS AS DISCRIBED
IN GS-47-0004



mat'l. code				surface	tolerance	projection	product family	
				ISO 1302	ISO 406	ISO 101	MINITEK	
ltr	ecn no	dr	date	tolerances unless otherwise specified			title	
A	F10338	LMU	03.10.01	angles	X	±0.3	UNSHR HEADER RIGHT ANGLE TMT	
B	F04-035	JCO	05.01.13	linear	X.X	±0.13		
C	F06-0210	LMU	06.07.05		X.XX	±0.05		
D	F08-0145	ELA	17.04.08	dr	L MULIN	04.09.28	dwg no	
E	B-19190	LMU	14.10.24	engr	J COMPAGNON	04.09.28	sheet 1 of 1	
F	F-25393	DDE	16.11.21	chr			size	
G	F-26943	DDE	17.05.10	appd	JM.C	04.09.28	A3	
sheet	revision						type	
index	sheet						CUSTOMER Drawing	